2SA1982

Silicon PNP epitaxial planar type

For low-frequency high breakdown voltage amplification Complementary to 2SC5346

■ Features

- \bullet Satisfactory forward current transfer ratio h_{FE} collector current I_{C} characteristics
- \bullet High collector to emitter voltage V_{CEO}
- Small collector output capacitance Cob
- Makes up a complementary pair with 2SC2631, which is optimum for the pre-driver stage of a 20 W to 40 W output amplifier

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector to base voltage	V_{CBO}	-150	V
Collector to emitter voltage	V _{CEO}	-150	V
Emitter to base voltage	V _{EBO}	-5	V
Peak collector current	I_{CP}	-100	mA
Collector current	I_{C}	-50	mA
Collector power dissipation *	P_{C}	1	W
Junction temperature	T _j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note) *: Printed circuit board: Copper foil area of 1 $\rm cm^2$ or more, and the board thickness of 1.7 mm for the collector portion

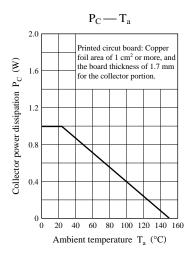
Unit: mm 6.9±0.1 0.7 4.0 0.65 max. 0.45±0.10 1.05±0.05 1. Emitter 2: Collector 3: Base MT-2-Al Package

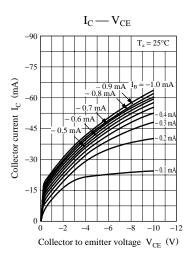
\blacksquare Electrical Characteristics $T_a = 25 ^{\circ} C$

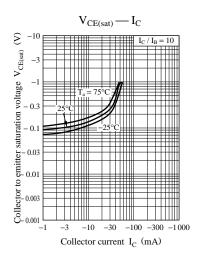
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector cutoff current	I _{CBO}	$V_{CB} = -100 \text{ V}, I_E = 0$			-1	μΑ
Collector to emitter voltage	V _{CEO}	$I_C = -0.1 \text{ mA}, I_B = 0$	-150			V
Emitter to base voltage	V _{EBO}	$I_E = -10 \mu\text{A}, I_C = 0$	-5			V
Forward current transfer ratio *	h _{FE}	$V_{CE} = -5 \text{ V}, I_{C} = -10 \text{ mA}$	130		330	
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = -30 \text{ mA}, I_B = -3 \text{ mA}$			-1	V
Noise voltage	NV	$V_{CE} = -10 \text{ V}, I_C = -1 \text{ mA}, G_V = 80 \text{ dB}$ $R_g = 100 \text{ k}\Omega, \text{Function} = \text{FLAT}$		150	300	mV
Transition frequency	f_T	$V_{CB} = -10 \text{ V}, I_E = 10 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$			5	pF

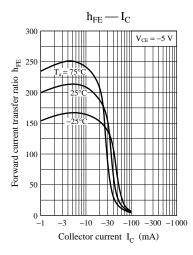
Note) *: h_{FE} Rank classification

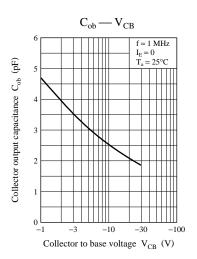
Rank	R	S
h_{FE}	130 to 220	185 to 330











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